

XP-002183611

AN - 1983-836782 [49]
A - [001] 013 03- 075 140 273 308 328 357 456 46& 463 477 506 509 623 627
628 723
AP - JP19820070729 19820427
CPY - KOBE
DC - A32 A85 L03 P73
FS - CPI;GMPI
IC - B32B5/22 ; B32B27/42 ; C08J5/24 ; H01B17/60 ; H05K1/03
KS - 0011 0034 0037 0216 0229 1277 2317 2467 2491 2544 2551 2718 2740
MC - A05-C01 A11-B09 A12-E07A A12-S08A L03-H04E1
PA - (KOBE) SHIN KOBE ELECTRIC MACHINERY
PN - JP58187434 A 19831101 DW198349 004pp
- JP62021813B B 19870514 DW198723 000pp
PR - JP19820070729 19820427
XA - C1983-119522
XIC - B32B-005/22 ; B32B-027/42 ; C08J-005/24 ; H01B-017/60 ; H05K-001/03
XP - N1983-218832
AB - J58187434 Mfr. comprises laminating and moulding prepregs. which are
produced by impregnating (a) phenol resin varnish into base material
by two stages, undercoating and top coating. Varnish (a) for the top
coating contains 0.5-5 pts. wt. of (b) aminocarboxylic acid salt cpd.
based on 100 pts. wt. of solid resin. Pref. cpd. (b) is that being
soluble or homogeneously dispersible in (a). It is e.g. EDTA,
diethylene triamine hexaacetic acid, diethanol glycine, etc.
- The laminated sheet is used as an insulated base plate of a printed
circuit plate. The laminated sheet prevents migration of silver in a
conductive coating for an electric circuit, since (b) reacts with
silver ion to form a water-insol. chelate.
- When the content of (b) is above 5 pts. wt., the laminated sheet
lowers in thermoresistance on soldering, chemical resistance, etc.(0/2)
IW - MANUFACTURE LAMINATE SHEET PCB BASE MOULD PREPREG BASED POLYPHENOL
RESIN VARNISH
IKW - MANUFACTURE LAMINATE SHEET PCB BASE MOULD PREPREG BASED POLYPHENOL
RESIN VARNISH
NC - 001
OPD - 1982-04-27
ORD - 1983-11-01
PAW - (KOBE) SHIN KOBE ELECTRIC MACHINERY
TI - Mfg. laminate sheet used as PCB base - by moulding prepregs based on
phenol] resin varnish